10A10G

10.0AMPS SILICON RECTIFIERS

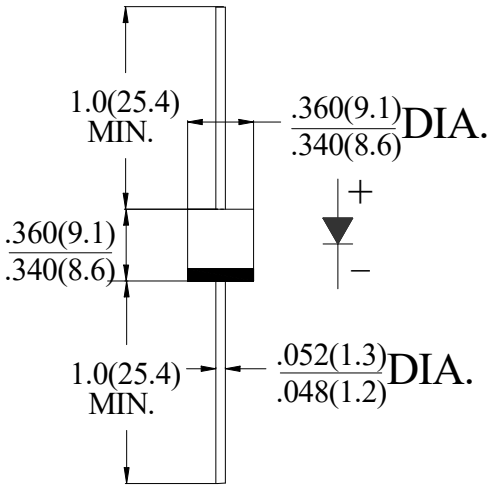
FEATURE

. High current capability
. Low forward voltage drop
. Low power loss, high efficiency
. High surge capability
. High temperature soldering guaranteed
260°C /1 0sec/0.375" lead length at 5 lbs tension

MECHANICAL DATA

. Terminal: Plated axial leads solderable per MIL-STD 202E, method 208C
. Case: Molded with UL-94 Class V-0 recognized Flame Retardant Epoxy
. Polarity: color band denotes cathode
. Mounting position: any

R-6



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25℃ ambient temperature unless otherwise specified.
Single phase, half wave, 60Hz,resistive or inductive load. For capacitive load, derate current by 20%

Type Number	SYMBOL	10A10G	units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS Voltage	V_{RMS}	700	V
Maximum DC blocking Voltage	V_{DC}	1000	V
Maximum Average Forward Rectified Current. 375" (9.5mm) lead length	$I_{F(AV)}$	10	A
Peak Forward Surge Current 8.3ms single half sine- wave superimposed on rated load (JEDEC method)	I_{FSM}	270	A
Maximum Forward Voltage at 10.0A DC	V_F	1.0	V
Maximum DC Reverse Current T_J =25°C	I_R	10	μA
at rated DC blocking voltage T_J=100°C		200	
Typical Junction Capacitance (Note1)	C_J	100	pF
Typical Thermal Resistance (Note2)	$R_{(JA)}$	40	°C/W
Storage Temperature	T_{STG}	-55 to +150	°C
Operation Junction Temperature	T_J	-55 to +150	°C

Note:

1. Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc
2. Thermal Resistance from Junction to Ambient at 0.375"（9.5mm）lead length

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

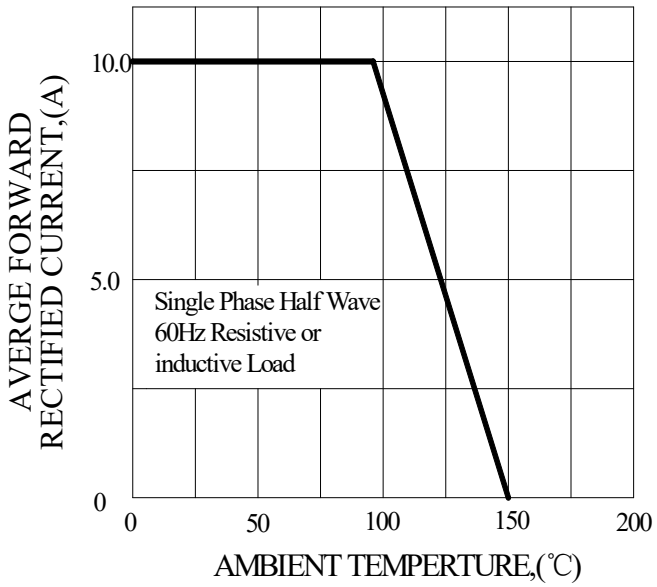


FIG.2-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

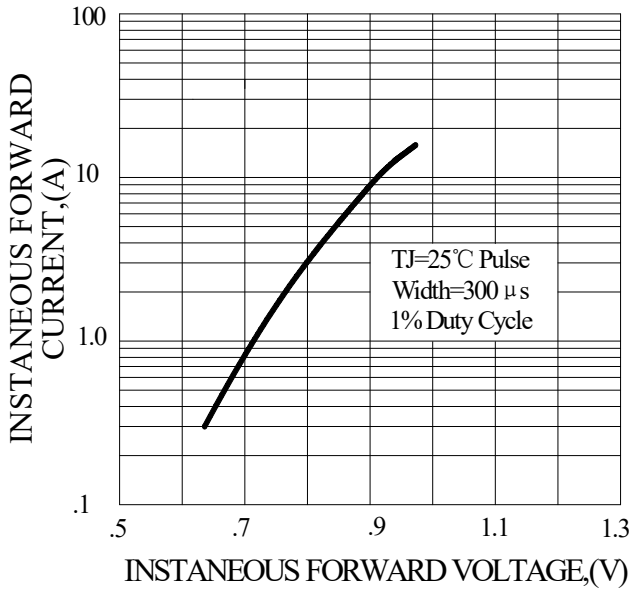


FIG.3-MAXIMUN NON-REPETITIVE FORWARD SURGE CURRENT

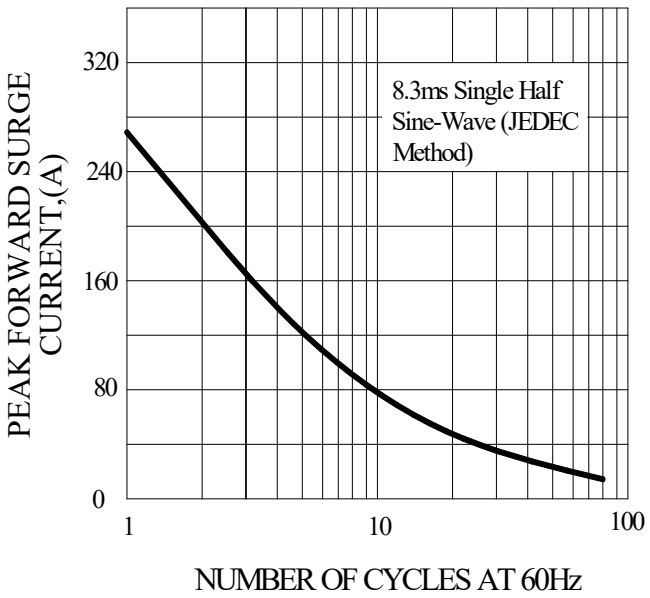
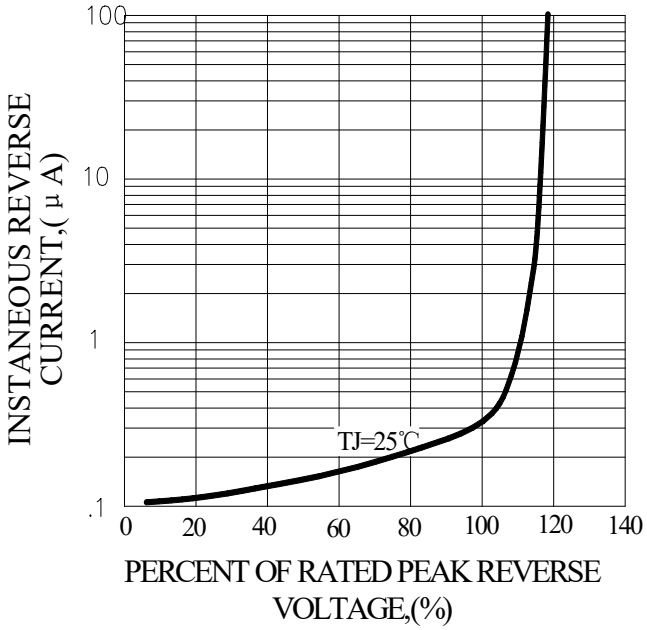
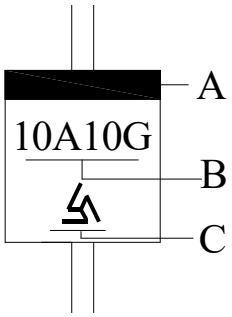


FIG.4-TYPICAL REVERSE CHARACTERISTICS



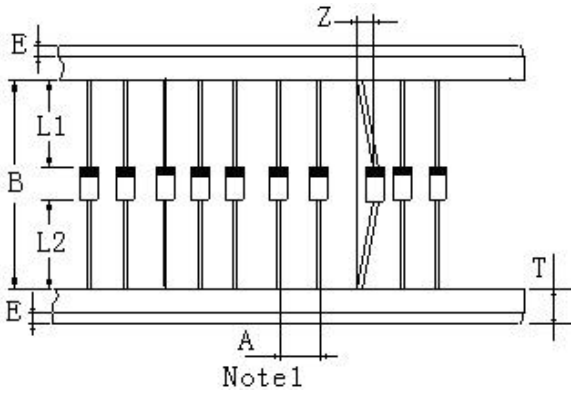
Marking and packaging illustration

1、Marking



SYMBOL	Explanation
A	Color Band Denotes Cathode
B	Product Name
C	Trademark

2、Packaging



ITEM	SYMBOL	SPECIFICATIONS (mm)	SPECIFICATIONS (inch)
Component alignment	Z	1.2max	0.048max
Tape width	T	6.0±0.4	0.236±0.016
Exposed adhesive	E	0.8max	0.032max
Body eccentricity	|L1-L2|	1.0max	0.040max
lead spacing	A	10.0±0.5	0.4±0.02
Tape span inside	B	52.0~53.5	2.06~2.11
NOTE： Each component lead shall be sandwiched between tapes for a minimum of 2.5mm（0.1inch）			